

PMP8735\_

Designator	Quantity	Value	Description	PackageReference	PartNumber	Manufacturer
C4	1	1500pF	CAP, CERM, 1500pF, 630V, X7R, xx%, [PackageReference]	1206	Used in BOM report	Used in BOM report
C5, C6	2	470uF	CAP, AL, 470uF, 10V, +/-20%, TH	D1000x1250mm	EGXL100ELL471MJC5S	Nippon Chemi-Con
C7, C8	2	47uF	CAP, CERM, 47uF, 10V, +/-10%, X7R, 1210	1210	GRM32ER71A476KE15 L	MuRata
C9	1	22uF	CAP, AL, 22uF, 25V, +/-20%, 1 ohm, SMD	SMT Radial D	EEE-FC1E220P	Panasonic
C10	1	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0805	0805	C2012X7R1E105K	TDK
C11	1	220pF	CAP, CERM, 220pF, 50V, +/-10%, X7R, 0603	0603	C0603C221K5RACTU	Kemet
C12	1	0.01uF	CAP, CERM, 0.01uF, 50V, +/-5%, X7R, 0603	0603	C0603C103J5RACTU	Kemet
C13	1	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603	C0603C101J5GACTU	Kemet
C14	1	0.01uF	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	0603	C0603C103K5RACTU	Kemet
C15	1	DNP	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0805	Used in BOM report	Used in BOM report
C16	1	DNP	CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	0603	Used in BOM report	Used in BOM report
C17, C18	2	3300pF	Capacitor, Ceramic Disk, 220V	0.394 X 0.315 inch Max.	ECKANA332ME	Panasonic
D2	1	400V	Diode, Ultrafast, 1000V, 1A, SMA	SMA	US1G	Diodes Inc.
D3	1	35V	Diode, Schottky, 35V, 16A, DPAK	DDPAK	MBRB1635PBF	Vishay-Semiconductor
D4	1	100V	Diode, Ultrafast, 75V, 0.3A, SOT-23	SOT-23	BAS19	Diodes Inc.
D5	1	15V	DIODE ZENER 15V 500MW SOD-123	SOD123	MMSZ5245BT	On Semi
J2, J4	2	PEC02DAAN	Header, 2x2-pin, 100mil spacing	0.20 x 0.20 inch	PEC02DAAN	Sullins
J5	1	PEC04DAAN	Header, Male 2x4-pin, 100mil spacing	0.20 x 0.40 inch	PEC04DAAN	Sullins
Q1	1	BSS126	MOSFET, Nch, 600V, 7 mA, 700 Ohm	SOT23	BSS126	Infineon
Q2	1	SPD03N60C3	MOSFET, Nch, 650V, 3.2 mA, 1.4 Ohm	DPAK	SPD03N60C3	Infineon
R1, R4	2	10k	RES, 10k ohm, 5%, 0.25W, 1206	1206	CRCW120610K0JNEA	Vishay-Dale
R2	1	100	RES, xxx ohm, x%, xW, [PackageReference]	1206	Used in BOM report	Used in BOM report
R3	1	120k	RES, xxx ohm, x%, xW, [PackageReference]	1210	Used in BOM report	Used in BOM report
R5	1	2.2Meg	RES, 2.2Meg ohm, 5%, 0.125W, 0805	0805	CRCW08052M20JNEA	Vishay-Dale
R6	1	100	RES, 100 ohm, 1%, 0.125W, 0805	0805	CRCW0805100RFKEA	Vishay-Dale
R7	1	40.2k	RES, 23.7k ohm, 1%, 0.1W, 0603	0603	CRCW060323K7FKEA	Vishay-Dale
R8	1	49.9	RES, 49.9 ohm, 1%, 0.1W, 0603	0603	CRCW060349R9FKEA	Vishay-Dale
R9	1	0	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R10	1	2.80k	RES, 2.80k ohm, 1%, 0.1W, 0603	0603	CRCW06032K80FKEA	Vishay-Dale
R11	1	9.76k	RES, 5.36k ohm, 1%, 0.1W, 0603	0603	CRCW06035K36FKEA	Vishay-Dale
R12, R16, R17	3	DNP	RES, xxx ohm, x%, xW, [PackageReference]	0603	Used in BOM report	Used in BOM report
R13	1	20.0k	RES, 20.0k ohm, 1%, 0.1W, 0603	0603	CRCW060320K0FKEA	Vishay-Dale
R14	1	0.82	RES, 0.82 ohm, 1%, 0.125W, 0805	0805	ERJ-6RQFR82V	Panasonic
R15	1	2k	RES, 10.0k ohm, 1%, 0.1W, 0603	0603	CRCW060310K0FKEA	Vishay-Dale
R18	1	6.49k	RES, 6.49k ohm, 1%, 0.1W, 0603	0603	CRCW06036K49FKEA	Vishay-Dale
T1	1	1.31mH	Transformer, 1.31mH, SMT	20.6x13.5x16.6mm	760871113	Würth Elektronik eiSos
TP3, TP4	2	Double	Terminal, Turret, TH, Double	Keystone1503-2	1503-2	Keystone
TP5	1	Red	Test Point, TH, Miniature, Red	Keystone5000	5000	Keystone
TP6	1	Black	Test Point, Miniature, Black, TH	Black Miniature Testpoint	5001	Keystone
U1	1	LM5023MM	IC, AC-DC Quasi-Resonant Current Mode PWM Controller	MSOP	LM5023MM	National Semi
U2	1	FOD817A	IC, Optocoupler, xx-V, yy% CTR	SMT-4PDIP	FOD817xx	Fairchild
U3	1		Low-Voltage (1.24V) Adjustable Precision Shunt Regulators, 3-pin SOT-23, Pb-Free	MF03A	LMV431AIMFX/NOPB	National Semiconductor

Notes:  
 Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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